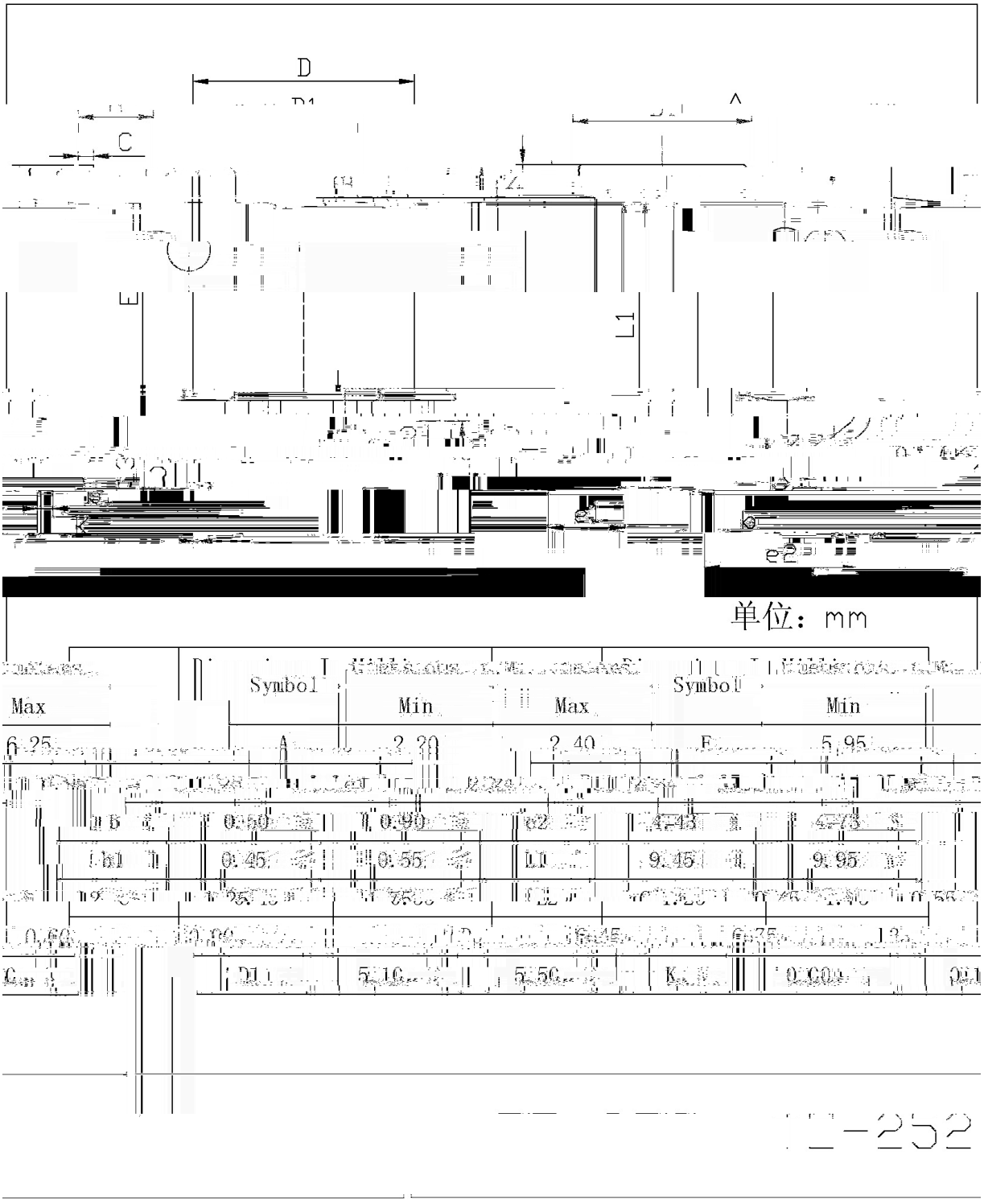
TO-252

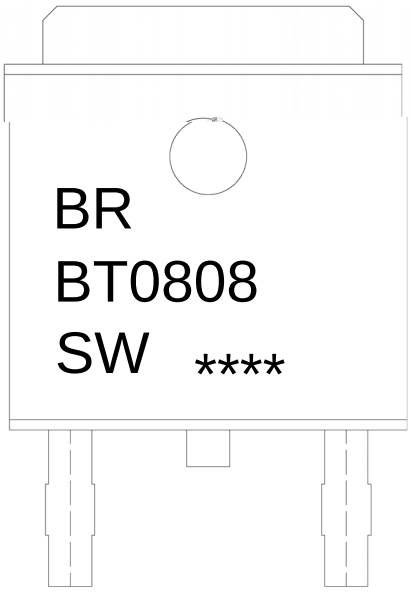
Triac in a TO-252 Plastic Package.

Parameter	Symbol	Rating	Unit
Repetitive peak off-state/reverse voltages(T_j=125)	V_{DRM}/V_{RRM}	800	V
RMS on-state current(T_C=110)	$I_{T(RMS)}$	8	A
Non repetitive surge peak on-state current(full cycle, T_j=25°C)	$I_{TSM(t=20ms)}$	80	A
I^2t value for fusing(T_j=25)	$I^2t_{(tp=10ms)}$	32	A^2s
Critical rate of rise of on-state current (I_G =2I_{GT}, f=120Hz T_j=125)	dI/dt I-II-III	50	A/μs
Peak gate current(t_p =20μs T_j=125)	I_{GM}	4.0	A
Average gate power dissipation(T_j=125)	$P_{G(AV)}$	1.0	W
Operating junction temperature range	T_j	-40 125	
Storage junction temperature range	T_{stg}	-40 150	
Junction to ambient(AC)	$R_{th(j-a)}$	100	/W
Junction to case for(AC)	$R_{th(j-c)}$	3.1	

/ Package Dimensions



/ Marking Instructions



BR	
BT0808	
SW	I_{GT}
****	

Note:

BR:	Company Code
BT0808:	Product Type Code
SW:	I_{GT} Bracket code
****:	Lot No. Code, code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

			Note:
1	150 180	60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5	5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3	2 10	/sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit：mm³)
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